

Title (en)

WIRING STRUCTURE AND PREPARATION METHOD THEREFOR, OLED ARRAY SUBSTRATE AND DISPLAY DEVICE

Title (de)

VERDRAHTUNGSSTRUKTUR UND HERSTELLUNGSVERFAHREN DAFÜR SOWIE OLED-ARRAYSUBSTRAT UND ANZEIGEVORRICHTUNG

Title (fr)

STRUCTURE DE CÂBLAGE ET SON PROCÉDÉ DE PRÉPARATION, ET SUBSTRAT DE RÉSEAU OLED ET DISPOSITIF D'AFFICHAGE

Publication

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Application

EP 18800457 A 20180511

Priority

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- CN 2018086460 W 20180511

Abstract (en)

[origin: US2019363155A1] A wiring structure and a manufacture method thereof, an organic light-emitting diode (OLED) array substrate and a display device are provided, the wiring structure includes: a base substrate, the base substrate includes a first surface and a second surface which are opposite to each other; a first conductive pattern arranged on the first surface of the base substrate and a second conductive pattern arranged on the second surface of the base substrate; the first conductive pattern is connected with the second conductive pattern through a via hole pattern penetrating through the base substrate. In the case that the wiring structure is applied to the organic light-emitting diode (OLED) array substrate, the display uniformity can be improved.

IPC 8 full level

H01L 27/12 (2006.01); **H01L 27/32** (2006.01)

CPC (source: CN EP US)

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Citation (search report)

- [X1] CN 106653819 A 20170510 - BOE TECHNOLOGY GROUP CO LTD, et al & EP 3584840 A1 20191225 - BOE TECHNOLOGY GROUP CO LTD [CN], et al
- [X1] US 2015021081 A1 20150122 - MITARAI SHUN [JP], et al
- [X1] US 2013038581 A1 20130214 - YAGI IWAO [JP]
- [A] US 2017124952 A1 20170504 - ZHANG BAOXIA [CN], et al
- [A] US 2004183083 A1 20040923 - KOO JAE-BON [KR]
- See also references of WO 2019024565A1

Designated contracting state (EPC)

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DOCDB simple family (publication)

US 10868103 B2 20201215; **US 2019363155 A1 20191128**; CN 109390351 A 20190226; CN 109390351 B 20210122; EP 3664138 A1 20200610; EP 3664138 A4 20210526; JP 2020529097 A 20201001; JP 7156952 B2 20221019; WO 2019024565 A1 20190207

DOCDB simple family (application)

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